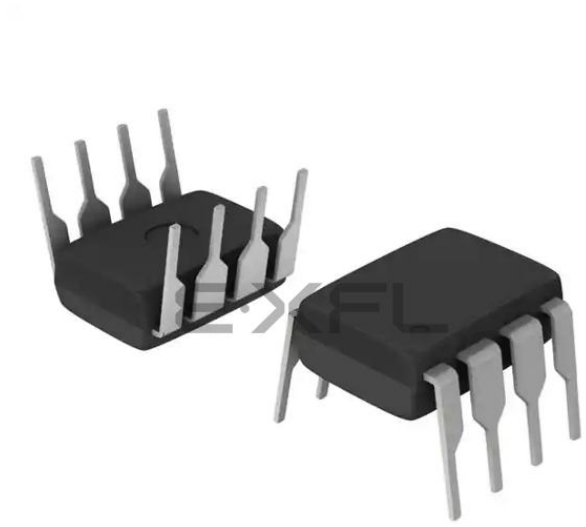

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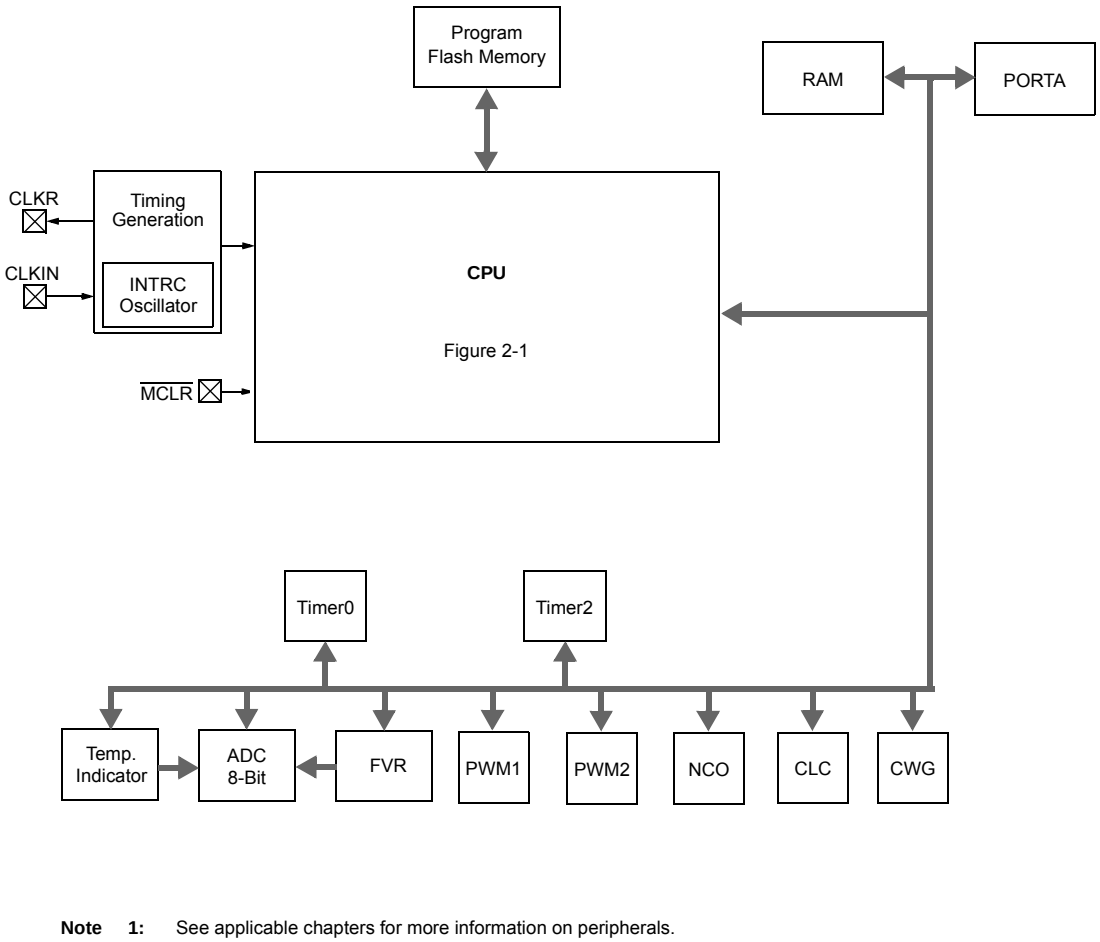
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	3
Program Memory Size	896B (512 x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 3x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic10lf322-e-p

FIGURE 1-1: PIC10(L)F320/322 BLOCK DIAGRAM



Note 1: See applicable chapters for more information on peripherals.

9.2.3 ERASING FLASH PROGRAM MEMORY

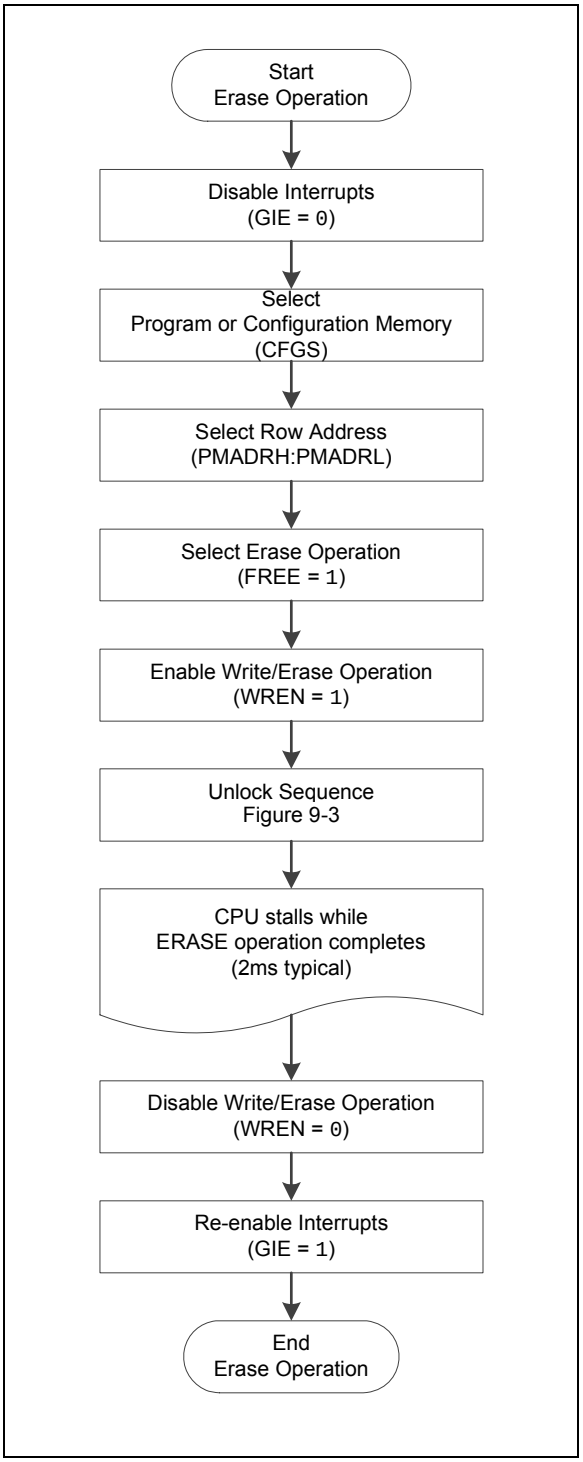
While executing code, program memory can only be erased by rows. To erase a row:

1. Load the PMADRH:PMADRL register pair with any address within the row to be erased.
2. Clear the CFGS bit of the PMCON1 register.
3. Set the FREE and WREN bits of the PMCON1 register.
4. Write 55h, then AAh, to PMCON2 (Flash programming unlock sequence).
5. Set control bit WR of the PMCON1 register to begin the erase operation.

See Example 9-2.

After the "`BSF PMCON1,WR`" instruction, the processor requires two cycles to set up the erase operation. The user must place two `NOP` instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms erase time. This is not Sleep mode as the clocks and peripherals will continue to run. After the erase cycle, the processor will resume operation with the third instruction after the PMCON1 write instruction.

FIGURE 9-4: FLASH PROGRAM MEMORY ERASE FLOWCHART



EXAMPLE 9-2: ERASING ONE ROW OF PROGRAM MEMORY

```
; This row erase routine assumes the following:
; 1. A valid address within the erase row is loaded in ADDRH:ADDRL
; 2. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)


        BCF         INTCON,GIE      ; Disable ints so required sequences will execute properly
        BANKSEL     PMADRL          ; not required on devices with 1 Bank of SFRs
        MOVF        ADDRL,W         ; Load lower 8 bits of erase address boundary
        MOVWF       PMADRL
        MOVF        ADDRH,W         ; Load upper 6 bits of erase address boundary
        MOVWF       PMADRH
        BCF         PMCON1,CFGS     ; Not configuration space
        BSF         PMCON1,FREE     ; Specify an erase operation
        BSF         PMCON1,WREN     ; Enable writes

Required
Sequence
        MOVLW       55h             ; Start of required sequence to initiate erase
        MOVWF       PMCON2          ; Write 55h
        MOVLW       0AAh            ;
        MOVWF       PMCON2          ; Write AAh
        BSF         PMCON1,WR       ; Set WR bit to begin erase
        NOP                         ; NOP instructions are forced as processor starts
        NOP                         ; row erase of program memory.
                                    ;
                                    ; The processor stalls until the erase process is complete
                                    ; after erase processor continues with 3rd instruction

        BCF         PMCON1,WREN     ; Disable writes
        BSF         INTCON,GIE      ; Enable interrupts
```

REGISTER 9-6: PMCON2: PROGRAM MEMORY CONTROL 2 REGISTER

W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0	W-0/0
Program Memory Control Register 2							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **Flash Memory Unlock Pattern bits**

To unlock writes, a 55h must be written first, followed by an AAh, before setting the WR bit of the PMCON1 register. The value written to this register is used to unlock the writes. There are specific timing requirements on these writes.

TABLE 9-3: SUMMARY OF REGISTERS ASSOCIATED WITH FLASH PROGRAM MEMORY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	40
PMCON1	—	CFGS	LWLO	FREE	WRERR	WREN	WR	RD	65
PMCON2	Program Memory Control Register 2								66
PMADRL	PMADR<7:0>								64
PMADRH	—	—	—	—	—	—	—	PMADR8	64
PMDATL	PMDAT<7:0>								63
PMDATH	—	—	PMDAT<13:8>						63

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Flash program memory module.

TABLE 9-4: SUMMARY OF CONFIGURATION WORD WITH FLASH PROGRAM MEMORY

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG	13:8	—	—	—	WRT<1:0>		BORV	LPBOR	LVP	20
	7:0	$\overline{CP}$	$\overline{MCLR}$	$\overline{PWRTE}$	WDTE<1:0>		BOREN<1:0>		FOSC	

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Flash program memory.

10.2 Register Definitions: PORTA

REGISTER 10-1: PORTA: PORTA REGISTER

U-0	U-0	U-0	U-0	R-x/x	R/W-x/x	R/W-x/x	R/W-x/x
—	—	—	—	RA3	RA2	RA1	RA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **Unimplemented**: Read as ‘0’

bit 3-0 **RA<3:0>:** PORTA I/O Value bits (RA3 is read-only)

Note 1: Writes to PORTx are actually written to the corresponding LATx register. Reads from PORTx register return actual I/O pin values.

REGISTER 10-2: TRISA: PORTA TRI-STATE REGISTER

U-0	U-0	U-0	U-0	U-1	R/W-1/1	R/W-1/1	R/W-1/1
—	—	—	—	—(1)	TRISA2	TRISA1	TRISA0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **Unimplemented**: Read as ‘0’.

bit 3 **Unimplemented**: Read as ‘1’.

bit 2-0 **TRISA<2:0>:** RA<2:0> Port I/O Tri-State Control bits

1 = Port output driver is disabled
0 = Port output driver is enabled

Note 1: Unimplemented, read as ‘1’.

TABLE 10-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	—	—	—	ANSA2	ANSA1	ANSA0	70
IOCAF	—	—	—	—	IOCAF3	IOCAF2	IOCAF1	IOCAF0	76
IOCAN	—	—	—	—	IOCAN3	IOCAN2	IOCAN1	IOCAN0	75
IOCAP	—	—	—	—	IOCAP3	IOCAP2	IOCAP1	IOCAP0	75
LATA	—	—	—	—	—	LATA2	LATA1	LATA0	70
PORTA	—	—	—	—	RA3	RA2	RA1	RA0	69
TRISA	—	—	—	—	—(1)	TRISA2	TRISA1	TRISA0	69
WPUA	—	—	—	—	WPUA3	WPUA2	WPUA1	WPUA0	71

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

Note 1: Unimplemented, read as '1'.

FIGURE 11-1: INTERRUPT-ON-CHANGE BLOCK DIAGRAM

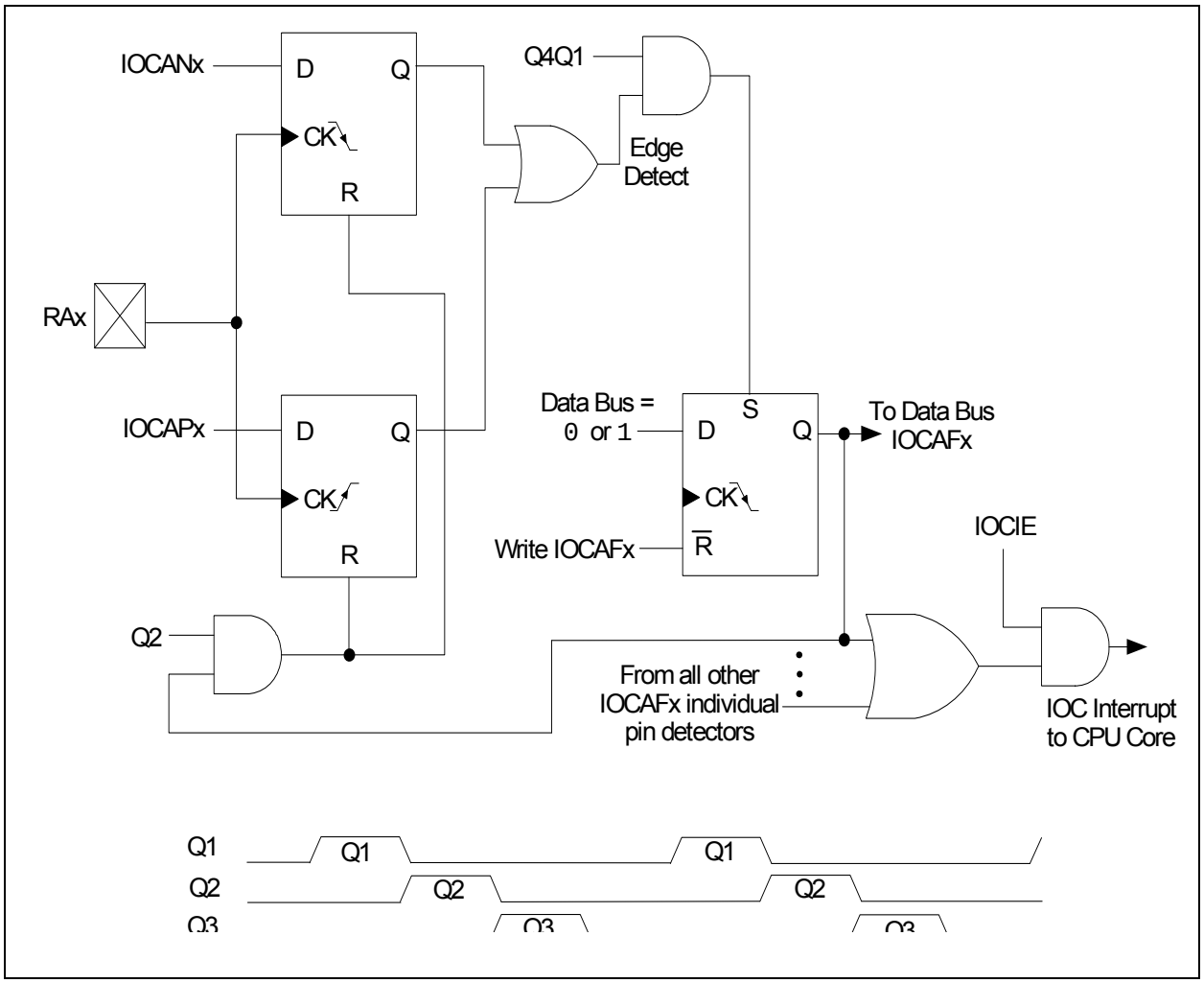


TABLE 15-1: ADC CLOCK PERIOD (T_{AD}) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (T_{AD})		Device Frequency (F_{OSC})			
ADC Clock Source	ADCS<2:0>	16 MHz	8 MHz	4 MHz	1 MHz
F_{OSC}/2	000	125 ns(1)	250 ns(1)	500 ns(1)	2.0 μs
F_{OSC}/4	100	250 ns(1)	500 ns(1)	1.0 μs	4.0 μs
F_{OSC}/8	001	0.5 μs(1)	1.0 μs	2.0 μs	8.0 μs(2)
F_{OSC}/16	101	1.0 μs	2.0 μs	4.0 μs	16.0 μs(2)
F_{OSC}/32	010	2.0 μs	4.0 μs	8.0 μs(2)	32.0 μs(2)
F_{OSC}/64	110	4.0 μs	8.0 μs(2)	16.0 μs(2)	64.0 μs(2)
FRC	x11	1.0-6.0 μs(1,3)	1.0-6.0 μs(1,3)	1.0-6.0 μs(1,3)	1.0-6.0 μs(1,3)

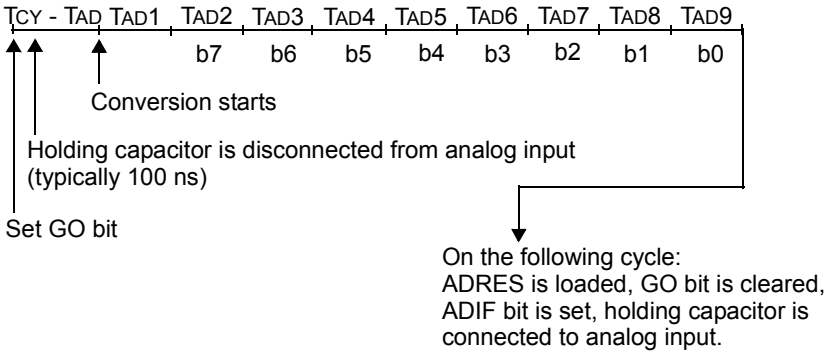
Legend: Shaded cells are outside of recommended range.

Note 1: These values violate the minimum required T_{AD} time.

2: For faster conversion times, the selection of another clock source is recommended.

3: The ADC clock period (T_{AD}) and total ADC conversion time can be minimized when the ADC clock is derived from the system clock F_{OSC}. However, the FRC clock source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 15-2: ANALOG-TO-DIGITAL CONVERSION T_{AD} CYCLES



18.1 PWMx Pin Configuration

All PWM outputs are multiplexed with the PORT data latch. The user must configure the pins as outputs by clearing the associated TRIS bits.

Note:	Clearing the PWMxOE bit will relinquish control of the PWMx pin.

18.1.1 FUNDAMENTAL OPERATION

The PWM module produces a 10-bit resolution output. Timer2 and PR2 set the period of the PWM. The PWMxDCL and PWMxDCH registers configure the duty cycle. The period is common to all PWM modules, whereas the duty cycle is independently controlled.

Note:	The Timer2 postscaler is not used in the determination of the PWM frequency. The postscaler could be used to have a servo update rate at a different frequency than the PWM output.

All PWM outputs associated with Timer2 are set when TMR2 is cleared. Each PWMx is cleared when TMR2 is equal to the value specified in the corresponding PWMxDCH (8 MSb) and PWMxDCL<7:6> (2 LSb) registers. When the value is greater than or equal to PR2, the PWM output is never cleared (100% duty cycle).

Note:	The PWMxDCH and PWMxDCL registers are double buffered. The buffers are updated when Timer2 matches PR2. Care should be taken to update both registers before the timer match occurs.

18.1.2 PWM OUTPUT POLARITY

The output polarity is inverted by setting the PWMxPOL bit of the PWMxCON register.

18.1.3 PWM PERIOD

The PWM period is specified by the PR2 register of Timer2. The PWM period can be calculated using the formula of Equation 18-1.

EQUATION 18-1: PWM PERIOD

$$PWM\ Period = [(PR2) + 1] \bullet 4 \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

Note: TOSC = 1/FOSC

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The PWM output is active. (Exception: When the PWM duty cycle = 0%, the PWM output will remain inactive.)
- The PWMxDCH and PWMxDCL register values are latched into the buffers.

Note:	The Timer2 postscaler has no effect on the PWM operation.

18.1.4 PWM DUTY CYCLE

The PWM duty cycle is specified by writing a 10-bit value to the PWMxDCH and PWMxDCL register pair. The PWMxDCH register contains the eight MSbs and the PWMxDCL<7:6>, the two LSbs. The PWMxDCH and PWMxDCL registers can be written to at any time.

Equation 18-2 is used to calculate the PWM pulse width.

Equation 18-3 is used to calculate the PWM duty cycle ratio.

EQUATION 18-2: PULSE WIDTH

$$Pulse\ Width = (PWMxDCH:PWMxDCL<7:6>) \bullet T_{OSC} \bullet (TMR2\ Prescale\ Value)$$

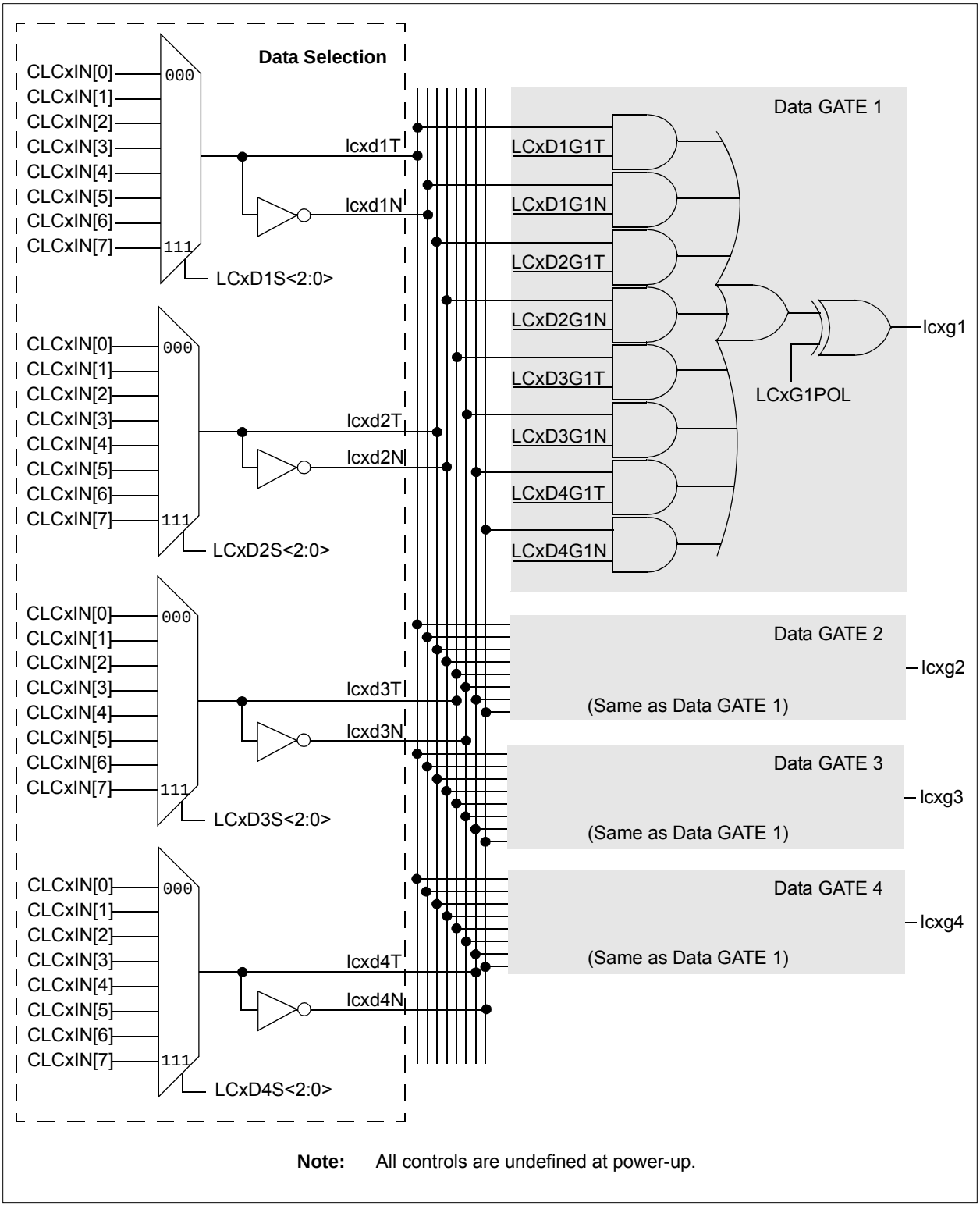
Note: TOSC = 1/FOSC

EQUATION 18-3: DUTY CYCLE RATIO

$$Duty\ Cycle\ Ratio = \frac{(PWMxDCH:PWMxDCL<7:6>)}{4(PR2 + 1)}$$

The 8-bit timer TMR2 register is concatenated with the two Least Significant bits of 1/FOSC, adjusted by the Timer2 prescaler to create the 10-bit time base. The system clock is used if the Timer2 prescaler is set to 1:1.

FIGURE 19-2: INPUT DATA SELECTION AND GATING



Note: All controls are undefined at power-up.

REGISTER 19-6: CLCxGLS1: GATE 2 LOGIC SELECT REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LCxG2D4T	LCxG2D4N	LCxG2D3T	LCxG2D3N	LCxG2D2T	LCxG2D2N	LCxG2D1T	LCxG2D1N
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **LCxG2D4T:** Gate 2 Data 4 True (non-inverted) bit
1 = lcxd4T is gated into lcxg2
0 = lcxd4T is not gated into lcxg2

bit 6 **LCxG2D4N:** Gate 2 Data 4 Negated (inverted) bit
1 = lcxd4N is gated into lcxg2
0 = lcxd4N is not gated into lcxg2

bit 5 **LCxG2D3T:** Gate 2 Data 3 True (non-inverted) bit
1 = lcxd3T is gated into lcxg2
0 = lcxd3T is not gated into lcxg2

bit 4 **LCxG2D3N:** Gate 2 Data 3 Negated (inverted) bit
1 = lcxd3N is gated into lcxg2
0 = lcxd3N is not gated into lcxg2

bit 3 **LCxG2D2T:** Gate 2 Data 2 True (non-inverted) bit
1 = lcxd2T is gated into lcxg2
0 = lcxd2T is not gated into lcxg2

bit 2 **LCxG2D2N:** Gate 2 Data 2 Negated (inverted) bit
1 = lcxd2N is gated into lcxg2
0 = lcxd2N is not gated into lcxg2

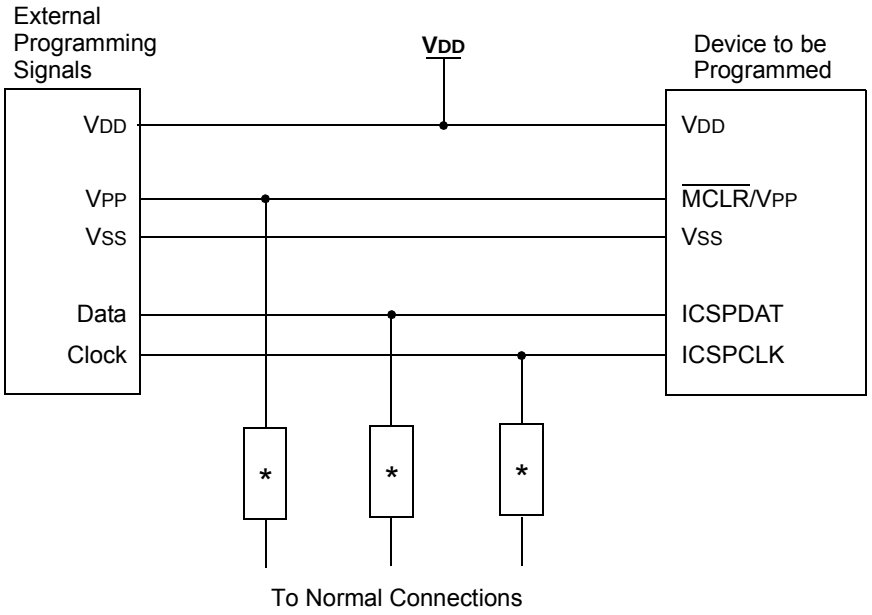
bit 1 **LCxG2D1T:** Gate 2 Data 1 True (non-inverted) bit
1 = lcxd1T is gated into lcxg2
0 = lcxd1T is not gated into lcxg2

bit 0 **LCxG2D1N:** Gate 2 Data 1 Negated (inverted) bit
1 = lcxd1N is gated into lcxg2
0 = lcxd1N is not gated into lcxg2

For additional interface recommendations, refer to your specific device programmer manual prior to PCB design.

It is recommended that isolation devices be used to separate the programming pins from other circuitry. The type of isolation is highly dependent on the specific application and may include devices such as resistors, diodes, or even jumpers. See Figure 22-3 for more information.

FIGURE 22-3: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



* Isolation devices (as required).

24.3 DC Characteristics

TABLE 24-1: SUPPLY VOLTAGE

PIC10LF320/322			Standard Operating Conditions (unless otherwise stated)				
PIC10F320/322							
Param. No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D001	VDD	**Supply Voltage**					
			1.8 2.5	— —	3.6 3.6	V V	FOSC ≤ 16 MHz: FOSC ≤ 20 MHz
D001			2.3 2.5	— —	5.5 5.5	V V	FOSC ≤ 16 MHz: FOSC ≤ 20 MHz
D002*	VDR	**RAM Data Retention Voltage(1)**					
			1.5	—	—	V	Device in Sleep mode
D002*			1.7	—	—	V	Device in Sleep mode
	VPOR*	**Power-on Reset Release Voltage**	—	1.6	—	V	
	VPORR*	**Power-on Reset Rearm Voltage**	—	0.8	—	V	Device in Sleep mode
			—	1.7	—	V	Device in Sleep mode
D003	VFVR	**Fixed Voltage Reference Voltage**					
		1x gain (1.024V nominal) 2x gain (2.048V nominal) 4x gain (4.096V nominal)	-8	—	+6	%	VDD ≥ 2.5V, -40°C ≤ TA ≤ +85°C VDD ≥ 2.5V, -40°C ≤ TA ≤ +85°C VDD ≥ 4.75V, -40°C ≤ TA ≤ +85°C
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 5.1 "Power-On Reset (POR)"** for details.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

FIGURE 24-7: CLKR AND I/O TIMING

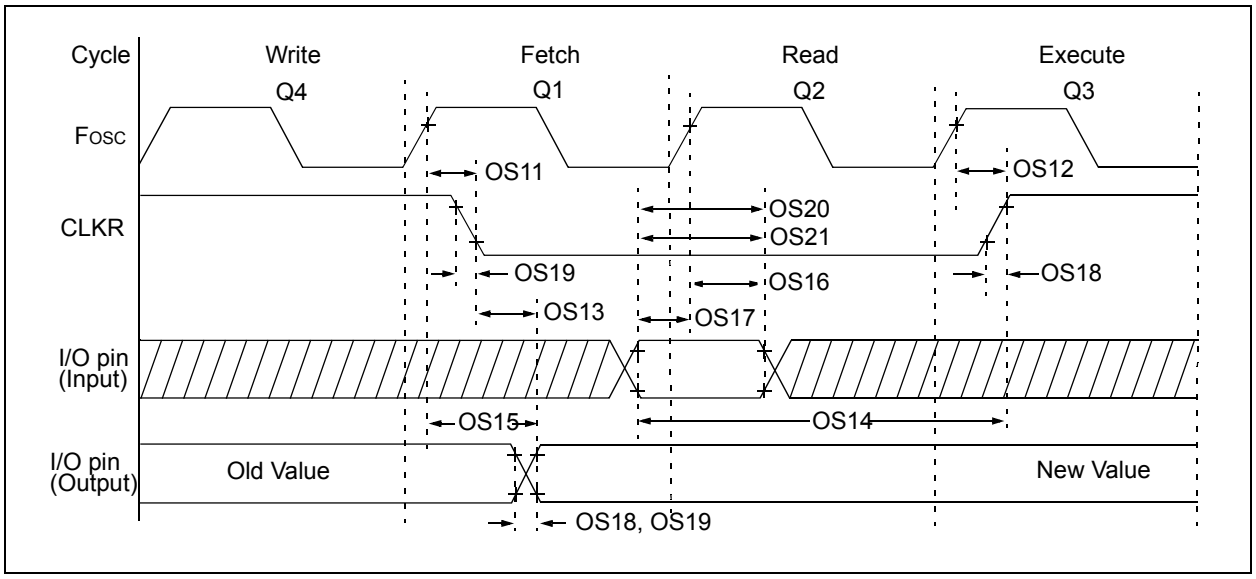


TABLE 24-8: CLKR AND I/O TIMING PARAMETERS

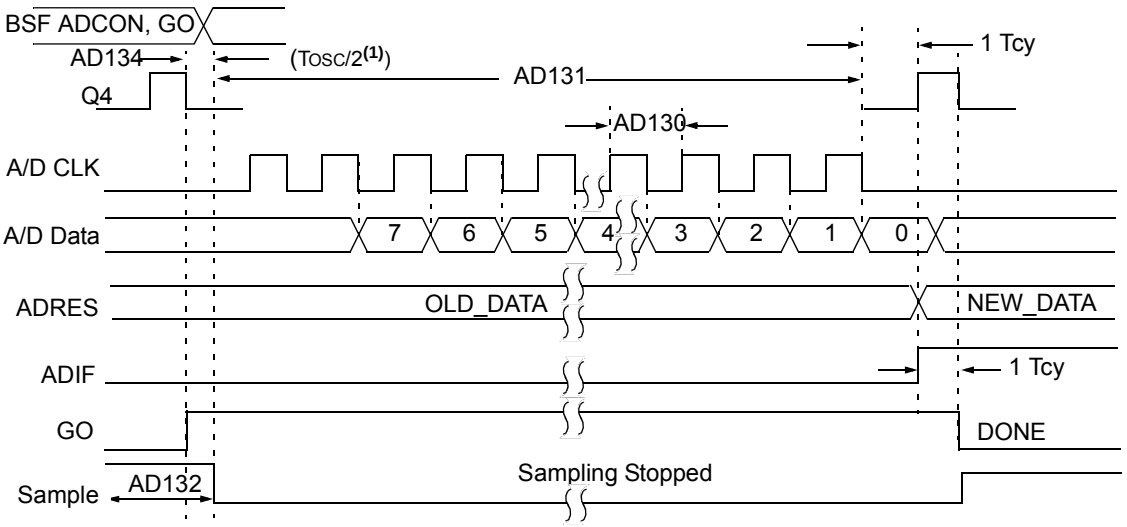
Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS11	TosH2ckL	FOSC↑ to CLKOUT↓(1)	—	—	70	ns	3.3V ≤ VDD ≤ 5.0V
OS12	TosH2ckH	FOSC↑ to CLKOUT↑(1)	—	—	72	ns	3.3V ≤ VDD ≤ 5.0V
OS13	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑(1)	TOSC + 200 ns	—	—	ns	
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	3.3V ≤ VDD ≤ 5.0V
OS16	TosH2ioI	Fosc↑ (Q2 cycle) to Port input invalid (I/O in setup time)	50	—	—	ns	3.3V ≤ VDD ≤ 5.0V
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18*	TioR	Port output rise time	— —	40 15	72 32	ns	VDD = 1.8V 3.3V ≤ VDD ≤ 5.0V
OS19*	TioF	Port output fall time	— —	28 15	55 30	ns	VDD = 1.8V 3.3V ≤ VDD ≤ 5.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Tioc	Interrupt-on-change new input level time	25	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated.

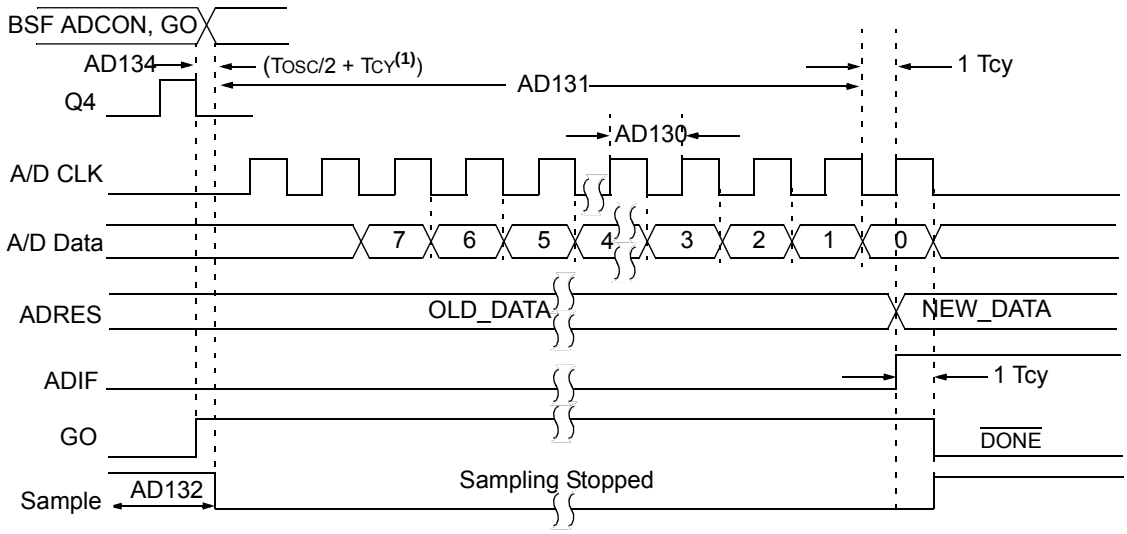
Note 1: Measurements are taken in EXTRC mode where CLKOUT output is 4 x TOSC.

FIGURE 24-12: A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as FRC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 24-13: A/D CONVERSION TIMING (SLEEP MODE)



Note 1: If the A/D clock source is selected as FRC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

26.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

26.12 Third-Party Development Tools

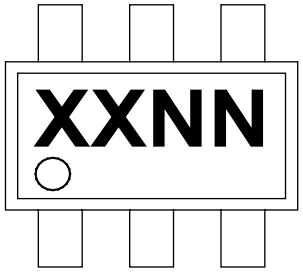
Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

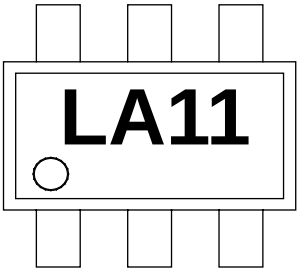
27.0 PACKAGING INFORMATION

27.1 Package Marking Information

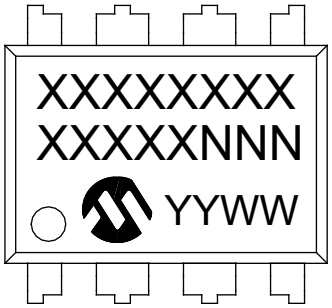
6-Lead SOT-23



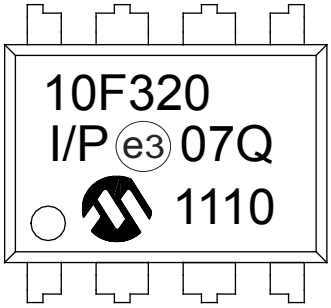
Example



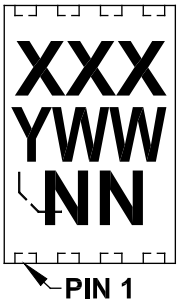
8-Lead PDIP (300 mil)



Example



8-Lead DFN (2x3x0.9 mm)



Example

Legend:	XX...X	Product-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

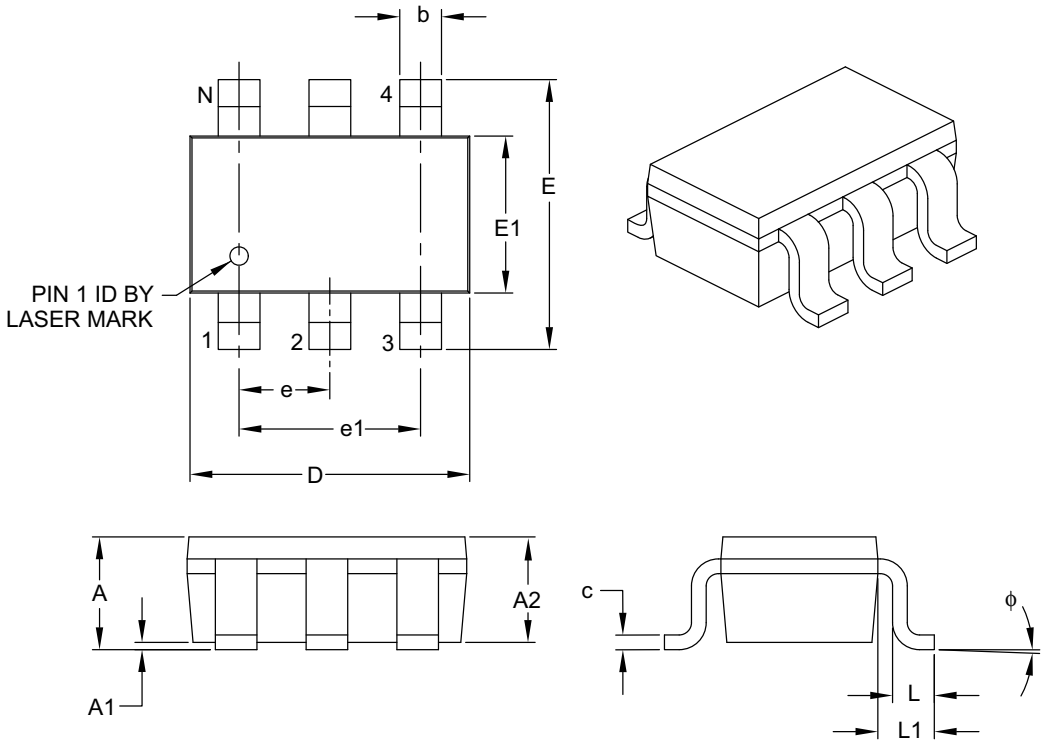
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

27.2 Package Details

The following sections give the technical details of the packages.

6-Lead Plastic Small Outline Transistor (OT) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		6	
Pitch	e		0.95 BSC	
Outside Lead Pitch	e1		1.90 BSC	
Overall Height	A	0.90	–	1.45
Molded Package Thickness	A2	0.89	–	1.30
Standoff	A1	0.00	–	0.15
Overall Width	E	2.20	–	3.20
Molded Package Width	E1	1.30	–	1.80
Overall Length	D	2.70	–	3.10
Foot Length	L	0.10	–	0.60
Footprint	L1	0.35	–	0.80
Foot Angle	ϕ	0°	–	30°
Lead Thickness	c	0.08	–	0.26
Lead Width	b	0.20	–	0.51

Notes:

1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
2. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-028B

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (07/2011)

Original release.

Revision B (02/2014)

Electrical Specifications update and new formats; Minor edits.

Revision C (05/2015)

Updated Figures 7-1 and 11-1. Update Sections 5.4.1, 24.1, and 24.3. Updated Tables 24-2 and 24-9.

Revision D (11/2015)

Updated the “eXtreme Low-Power (XLP) Features” section; added “Memory” section. Updated “Family Types” table; Updated Table 2-1, 24-5, 24-7, 24-9, 24-12 and 24-13; Updated Figure 7-1, 24-6 and section 15.2.5; Other minor corrections.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X](1)	-	X	/XX	XXX
Device	Tape and Reel Option		Temperature Range	Package	Pattern

Device:	PIC10F320, PIC10LF320, PIC10F322, PIC10LF322	
Tape and Reel Option:	Blank T	= Standard packaging (tube or tray) = Tape and Reel(1)
Temperature Range:	I E	= -40°C to +85°C (Industrial) = -40°C to +125°C (Extended)
Package:	OT P MC	= SOT-23 = PDIP = DFN
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)	

Examples:

a) PIC10LF320T - I/OT
Tape and Reel,
Industrial temperature,
SOT-23 package

b) PIC10F322 - I/P
Industrial temperature
PDIP package

c) PIC10F322 - E/MC
Extended temperature,
DFN package

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.